

## Description

The AP65353 is an adaptive constant on-time mode synchronous buck converter providing high efficiency, excellent transient response and high DC output accuracy for low-voltage regulation in digital TV and monitor.

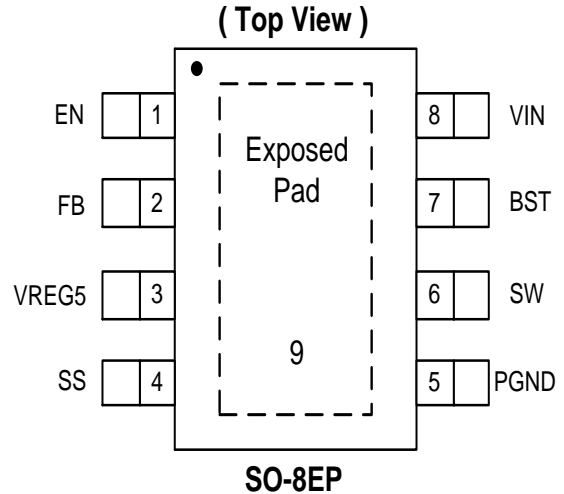
The constant-on-time control scheme handles wide input/output voltage ratios and provides low external component count. The internal proprietary circuit enables the device to adopt both low equivalent series resistance (ESR) output capacitors, such as SP-CAP or POSCAP and ultra-low ESR ceramic capacitors.

The adaptive on-time control supports seamless transition between continuous conduction mode (CCM) at higher load conditions and discontinuous conduction mode (DCM) at lighter load conditions.

DCM allows AP65353 to maintain high efficiency at light load conditions. The AP65353 also features programmable soft-start, UVLO, OTP, OVP and OCP to protect the circuit.

This IC is available in SO-8EP package.

## Pin Assignments



## Applications

- Gaming Consoles
- Flat Screen TV Sets and Monitors
- Set-Top Boxes
- Home Audio
- Consumer Electronics
- Network Systems
- Green

Notes:

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3).compliant.
2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

**Typical Applications Circuit**

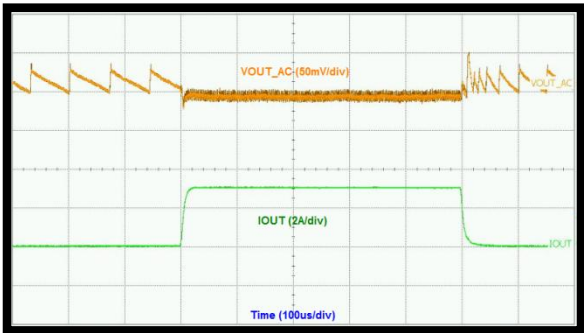
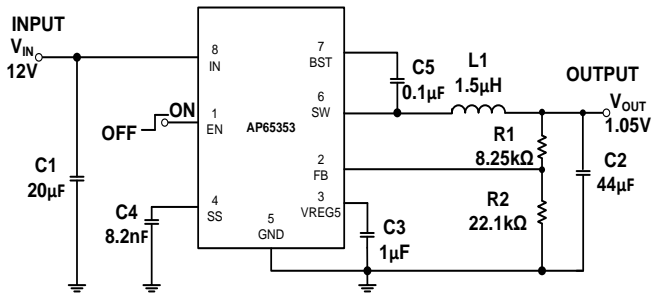


Figure 1 Typical Application Circuit

**Pin Descriptions**

| Pin Name | Pin Number         | Function  |
|----------|--------------------|---|
| EN       | 1                  | Enable input. EN is a digital input that turns the regulator on or off. Drive EN high to turn on the regulator, drive it low to turn off. EN can be safely connected to VIN directly for automatic startup.                           |
| FB       | 2                  | Feedback Input. FB senses the output voltage and regulates it. Drive FB with a resistive voltage divider connected to it from the output voltage.   |
| VREG5    | 3                  | Internal power supply output pin to connect an additional capacitor. Connect a 1µF (typical) capacitor as close as possible to the VREG5 and PGND. This pin is not active when EN is low.   |
| SS       | 4                  | Soft-start control input pin. SS controls the soft start period. Connect a capacitor from SS to PGND to set the soft-start period.  |
| SW       | 6                  | Power Switching Output. SW is the switching node that supplies power to the output. Connect the output LC filter from SW to the output load. Note that a capacitor is required from SW to BST to power the high-side switch.          |
| BST      | 7                  | Bootstrap pin. A bootstrap capacitor is connected between the BST pin and SW pin. The voltage across the bootstrap capacitor drives the internal high-side NMOS switch. A 0.1µF (typical) capacitor is required for proper operation. |
| VIN      | 8                  | Supply input. A capacitor should be connected between the VIN pin and PGND pin to keep the DC input voltage constant.   |
| PGND     | 5, 9 (Exposed Pad) | Power ground and GND. Exposed pad must be connected to as large of PGND plane as possible for maximum thermal performance.  |

**Functional Block Diagram**

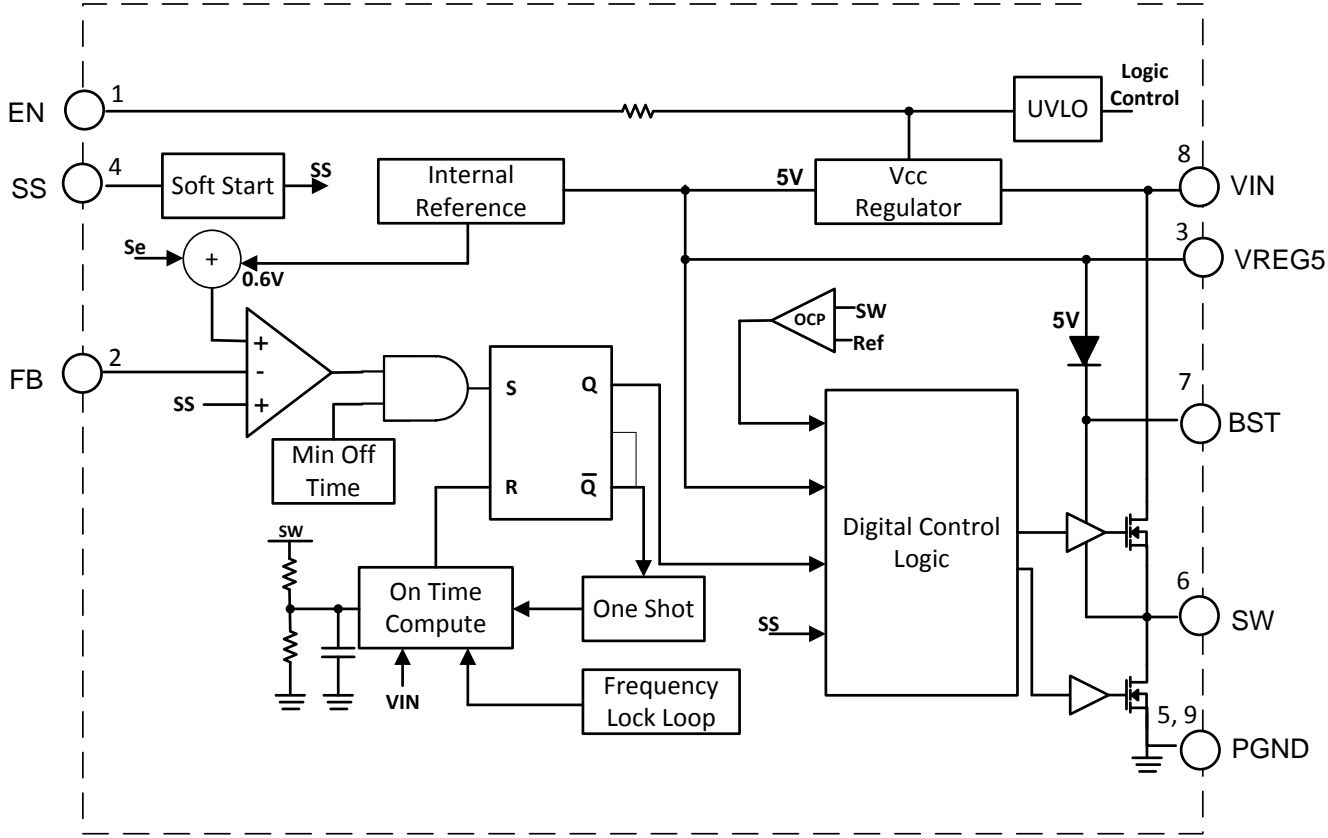


Figure 2 Functional Block Diagram

### Absolute Maximum Ratings (Note 4) (@T<sub>A</sub> = +25°C, unless otherwise specified.)

| Symbol            | Parameter                     | Rating                       | Unit |
|-------------------|-------------------------------|------------------------------|------|
| V <sub>IN</sub>   | Supply Voltage                | -0.3 to 20                   | V    |
| V <sub>REG5</sub> | V <sub>REG5</sub> Pin Voltage | -0.3V to +6.0                | V    |
| V <sub>SW</sub>   | Switch Node Voltage           | -1.0 to V <sub>IN</sub> +0.3 | V    |
| V <sub>BST</sub>  | Bootstrap Voltage             | -0.3 to V <sub>SW</sub> +6.0 | V    |
| V <sub>FB</sub>   | Feedback Voltage              | -0.3V to +6.0                | V    |
| V <sub>EN</sub>   | Enable/UVLO Voltage           | -0.3V to V <sub>IN</sub>     | V    |
| V <sub>SS</sub>   | Soft-start PIN                | -0.3V to +6.0                | V    |
| V <sub>PGND</sub> | PGND Pin Voltage              | -0.3 to 0.3                  | V    |
| T <sub>ST</sub>   | Storage Temperature           | -65 to +150                  | °C   |
| T <sub>J</sub>    | Junction Temperature          | +160                         | °C   |
| T <sub>L</sub>    | Lead Temperature              | +260                         | °C   |

### ESD Susceptibility (Note 5)

|     |                  |     |    |
|-----|------------------|-----|----|
| HBM | Human Body Model | 2   | kV |
| MM  | Machine Model    | 200 | V  |

- Notes:
- Stresses greater than the 'Absolute Maximum Ratings' specified above may cause permanent damage to the device. These are stress ratings only; functional operation of the device at these or any other conditions exceeding those indicated in this specification is not implied. Device reliability may be affected by exposure to absolute maximum rating conditions for extended periods of time.
  - Semiconductor devices are ESD sensitive and may be damaged by exposure to ESD events. Suitable ESD precautions should be taken when handling and transporting these devices.

### Thermal Resistance (Note 6)

| Symbol          | Parameter           | Rating |       | Unit |
|-----------------|---------------------|--------|-------|------|
| θ <sub>JA</sub> | Junction to Ambient | SO-8EP | 38.56 | °C/W |
| θ <sub>JC</sub> | Junction to Case    | SO-8EP | 6.85  | °C/W |

### Recommended Operating Conditions (Note 7) (@T<sub>A</sub> = +25°C, unless otherwise specified.)

| Symbol          | Parameter                            | Min | Max  | Unit |
|-----------------|--------------------------------------|-----|------|------|
| V <sub>IN</sub> | Supply Voltage                       | 4.5 | 18.0 | V    |
| T <sub>J</sub>  | Operating Junction Temperature Range | -40 | +125 | °C   |
| T <sub>A</sub>  | Operating Ambient Temperature Range  | -40 | +85  | °C   |

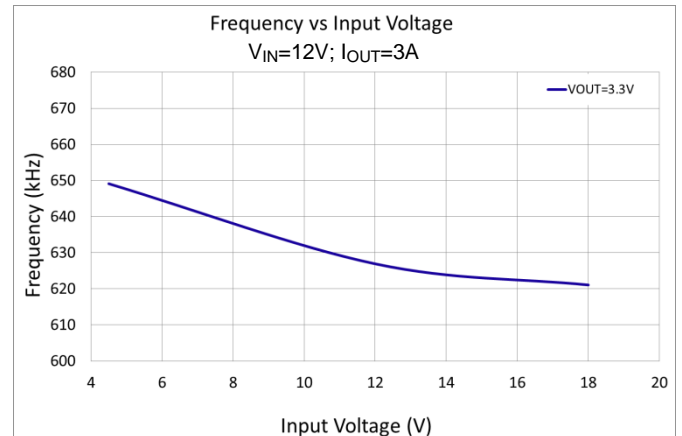
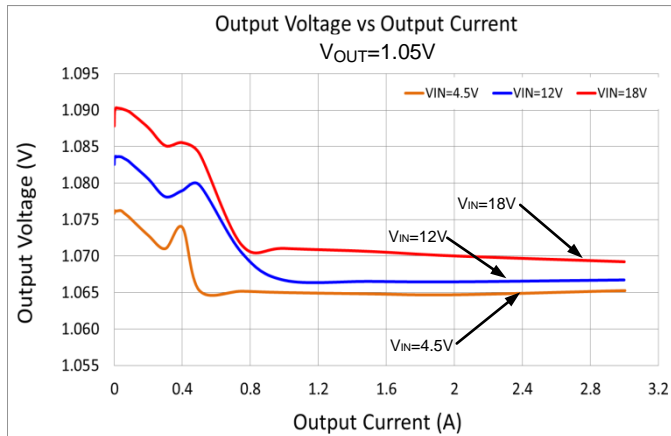
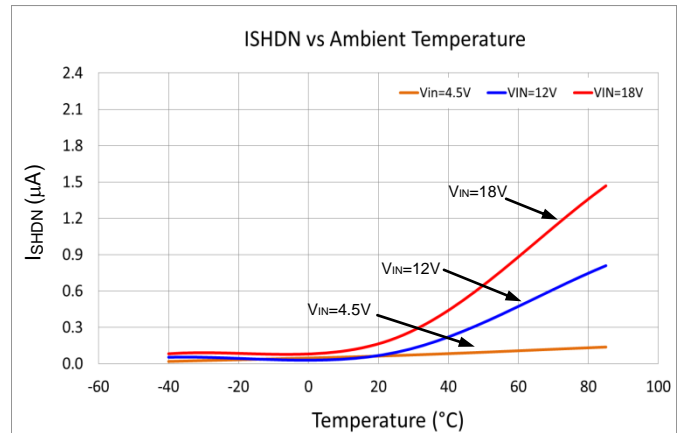
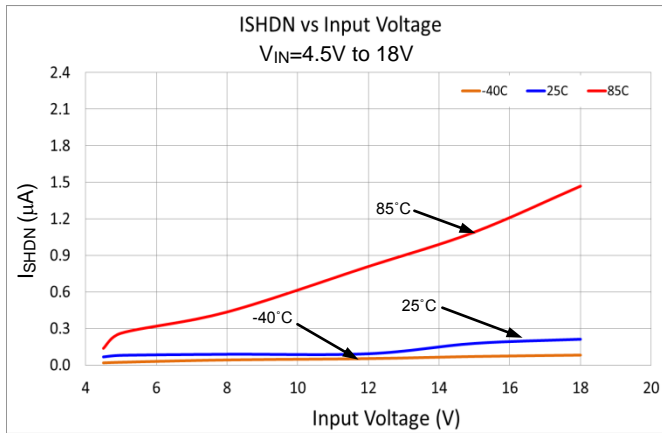
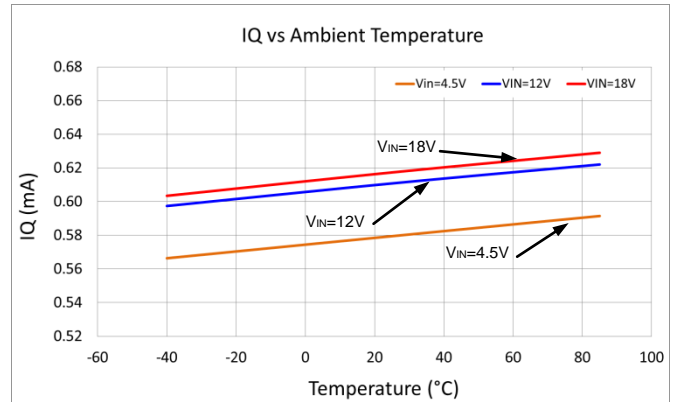
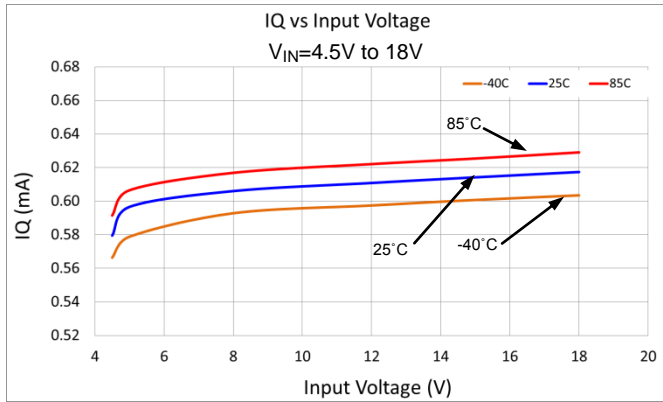
- Notes:
- Test condition: SO-8: Device mounted on 1" x 1" FR-4 substrate PCB, 2oz copper, with minimum recommended pad layout.
  - The device function is not guaranteed outside of the recommended operating conditions.

**Electrical Characteristics** (@ $T_A = +25^\circ\text{C}$ ,  $V_{IN} = 12\text{V}$ , unless otherwise specified.)

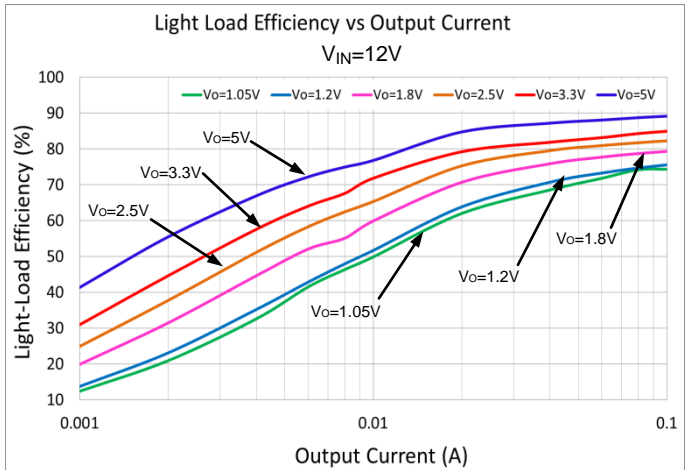
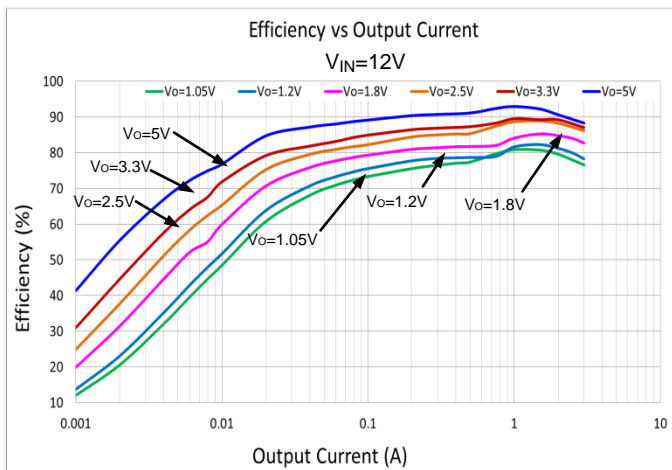
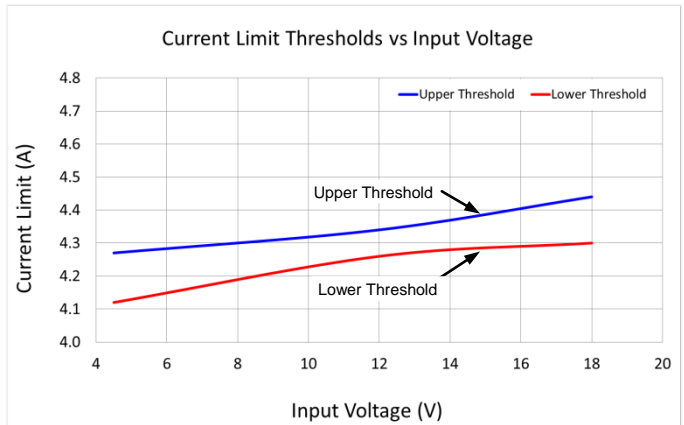
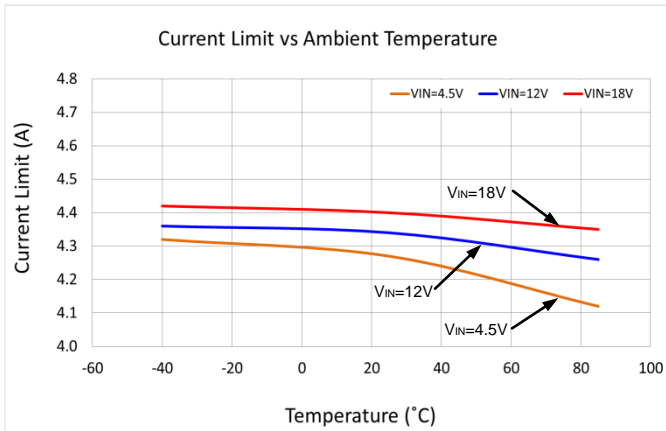
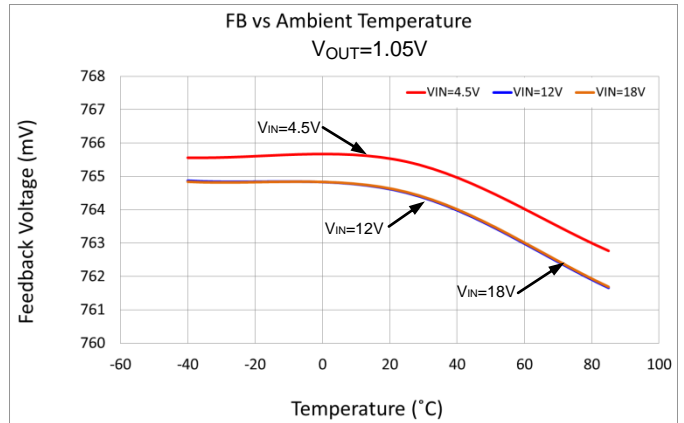
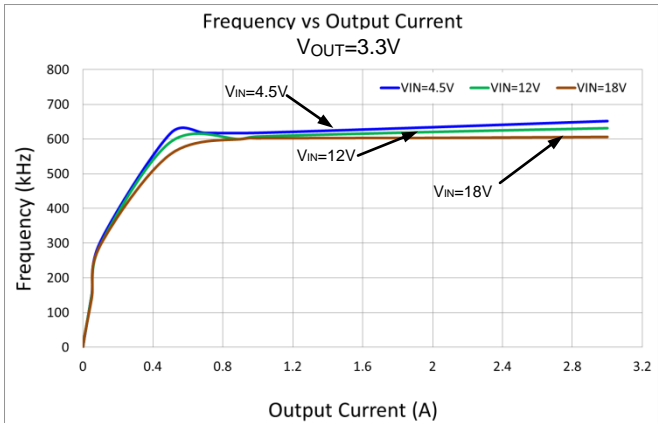
| Parameter                         | Symbol             | Conditions  | Min   | Typ   | Max   | Unit             |
|-----------------------------------|--------------------|---|-------|-------|-------|------------------|
| <b>SUPPLY VOLTAGE (VIN PIN)</b>   |                    |   |       |       |       |                  |
| Input Voltage                     | $V_{IN}$           | —   | 4.5   | —     | 18    | V                |
| Quiescent Current                 | $I_Q$              | $V_{FB} = 0.85\text{V}$   | —     | 0.6   | 0.75  | mA               |
| Shutdown Supply Current           | $I_{SHDN}$         | $V_{EN} = 0\text{V}$  | —     | 1     | 10    | $\mu\text{A}$    |
| <b>UNDERVOLTAGE LOCKOUT</b>       |                    |   |       |       |       |                  |
| UVLO Threshold                    | $V_{UVLO}$         | $V_{IN}$ Rising Test VREG5 Voltage  | 3.6   | 3.85  | 4.1   | V                |
| UVLO Hysteresis                   | $V_{HYS}$          | $V_{IN}$ Falling Test VREG5 Voltage   | 0.16  | 0.35  | 0.47  | V                |
| <b>ENABLE (EN PIN)</b>            |                    |   |       |       |       |                  |
| EN High-level Input Voltage       | $V_{ENH}$          | —   | 1.25  | —     | 18    | V                |
| EN Low-level Input Voltage        | $V_{ENL}$          | —   | —     | —     | 0.85  | V                |
| <b>VOLTAGE REFERENCE (FB PIN)</b> |                    |   |       |       |       |                  |
| Feedback Voltage                  | $V_{FB}$           | $V_{OUT} = 1.05\text{V}$ , , $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$ , CCM | 0.753 | 0.765 | 0.777 | V                |
| Feedback Bias Current             | $I_{FB}$           | $V_{FB} = 0.8\text{V}$  | -0.1  | 0     | 0.1   | $\mu\text{A}$    |
| <b>VREG5 OUTPUT</b>               |                    |   |       |       |       |                  |
| VREG5 Output Voltage              | $V_{VREG5}$        | $6.0\text{V} < V_{IN} < 18\text{V}$ $0 < I_{VREG5} < 5\text{mA}$                    | 4.8   | 5.1   | 5.4   | V                |
| Source Current Capability         | —                  | $V_{IN} = 6\text{V}$ , $V_{VREG5} = 4\text{V}$                                      | —     | 100   | —     | mA               |
| Load Regulation                   | —                  | $0 < I_{VREG5} < 5\text{mA}$  | —     | —     | 100   | mV               |
| Line Regulation                   | —                  | $6.0\text{V} < V_{IN} < 18\text{V}$ $I_{VREG5} = 5\text{mA}$                        | —     | —     | 20    | mV               |
| <b>MOSFET</b>                     |                    |   |       |       |       |                  |
| High-side Switch On-resistance    | $R_{DS(ON)H}$      | —   | —     | 90    | —     | m $\Omega$       |
| Low-side Switch On-resistance     | $R_{DS(ON)L}$      | —   | —     | 57    | —     | m $\Omega$       |
| <b>CURRENT LIMIT</b>              |                    |   |       |       |       |                  |
| High-level Current Limit          | $I_{LIM-H}$        | $L = 1.5\mu\text{H}$ , $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$             | 3.9   | 4.5   | 5.5   | A                |
| <b>ON-TIME TIMER</b>              |                    |   |       |       |       |                  |
| On Time                           | $t_{ON}$           | $V_{IN} = 12\text{V}$ , $V_{OUT} = 1.05\text{V}$                                    | —     | 150   | —     | ns               |
| Minimum Off Time                  | $t_{OFF-MIN}$      | $V_{FB} = 0.7\text{V}$  | —     | 260   | 310   | ns               |
| <b>THERMAL SHUTDOWN</b>           |                    |   |       |       |       |                  |
| Thermal Shutdown                  | $T_{OTSD}$         | —   | —     | 150   | —     | $^\circ\text{C}$ |
| Thermal Shutdown Hysteresis       | $T_{HYS}$          | —   | —     | 25    | —     | $^\circ\text{C}$ |
| <b>SOFT START (SS PIN)</b>        |                    |   |       |       |       |                  |
| Soft-start Source Current         | $I_{SS-SOURCE}$    | $V_{SS} = 1.0\text{V}$  | 4.2   | 6.0   | 7.8   | $\mu\text{A}$    |
| Soft-start Discharge Current      | $I_{SS-DISCHARGE}$ | $V_{SS} = 0.5\text{V}$  | 0.1   | 0.2   | —     | mA               |
| <b>OVERVOLTAGE PROTECTION</b>     |                    |   |       |       |       |                  |
| OVP Trip Threshold                | —                  | —   | 115   | 120   | 125   | %                |

Note: 8. Compliance to the datasheet limits is assured by one or more methods: production test, characterization, and/or design.

**Typical Performance Characteristics** (@ $T_A = +25^\circ\text{C}$ ,  $V_{IN} = 12\text{V}$ ,  $V_{OUT} = 1.05\text{V}$ , unless otherwise specified.)

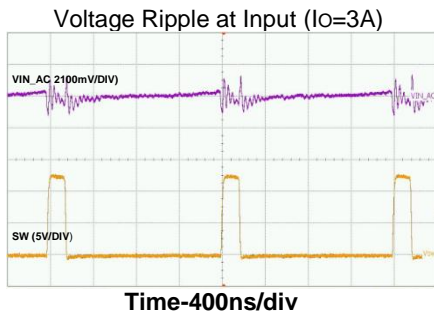
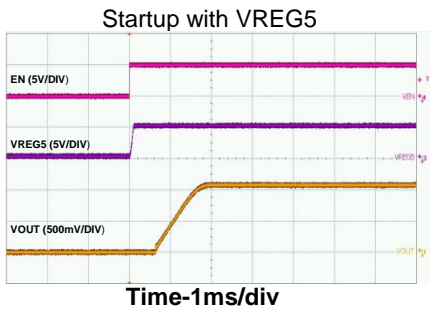
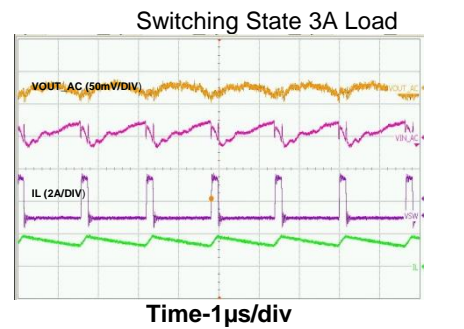
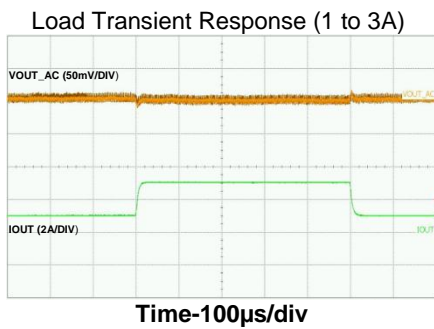
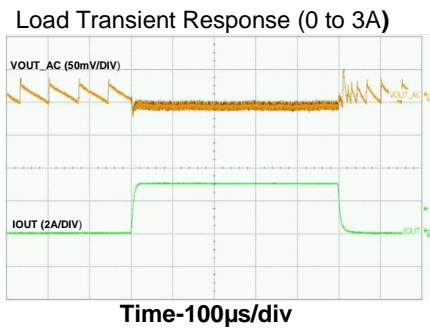
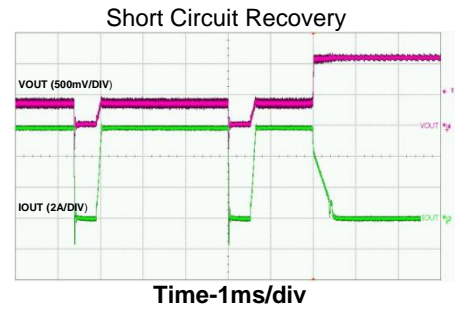
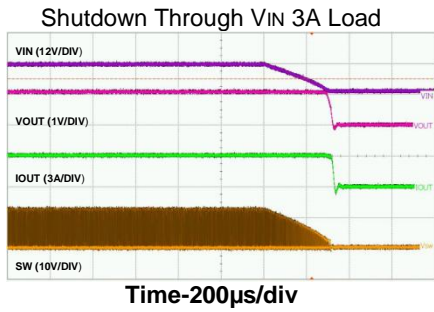
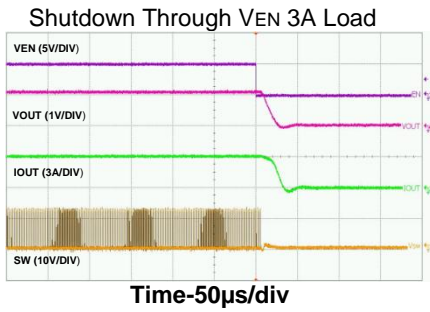
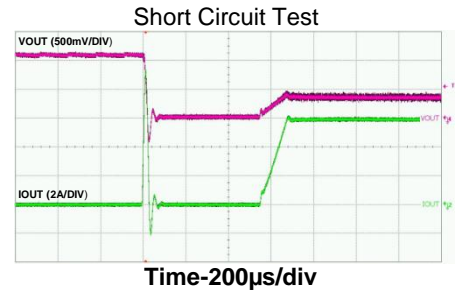
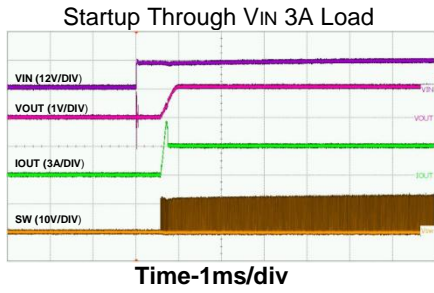
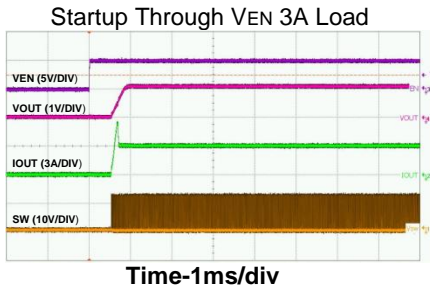


**Typical Performance Characteristics** (continued) (@ $T_A = +25^\circ\text{C}$ ,  $V_{IN} = 12\text{V}$ ,  $V_{OUT} = 1.05\text{V}$ , unless otherwise specified.)



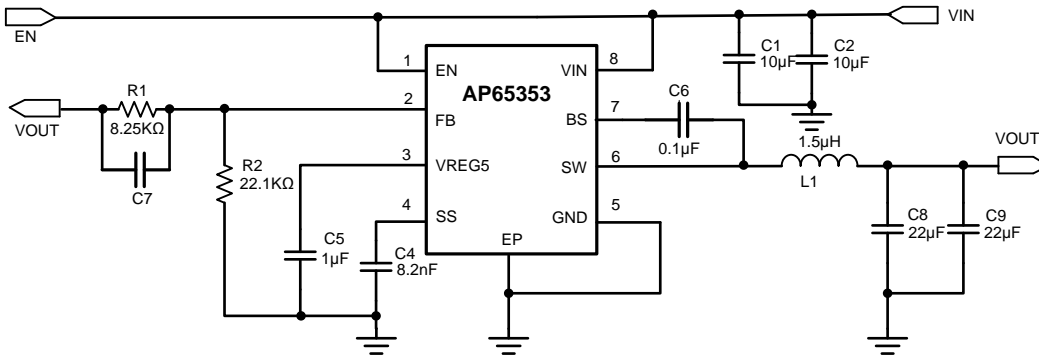
**Typical Performance Characteristics (cont.)**

(@T<sub>A</sub> = +25°C, V<sub>IN</sub> = 12V, V<sub>OUT</sub> = 1.05V, L = 1.5μH, C1 = 20μF, C2 = 44μF, unless otherwise specified.)





**Application Information**



**Figure 3 Typical Application of AP65353 Evaluation Board**

**PWM Operation and Adaptive On-time Control**

The AP65353 is a synchronous step-down converter with internal power MOSFETs. Adaptive constant on-time (aCOT) control is employed to provide fast, transient response and easy loop stabilization. At the beginning of each cycle, the high-side MOSFET is turned on for a fixed one shot timer, ON-time period. This one shot is calculated by the converter’s input voltage (VIN) and the output voltage (VOUT) cycle-by-cycle based to maintain a pseudo-fixed frequency over the input voltage range, hence it is called adaptive on-time control. The high-side MOSFET turns off after the fixed on time expires and turns on the low-side MOSFET. Once the output voltage dropped below the output regulation, the low-side turned off. The one-shot timer then reset and the high-side MOSFET is turned on again.

AP65353 uses an adaptive on-time control scheme and does not have a dedicated in-board oscillator. It runs with a pseudo-constant frequency of 650kHz by using the input voltage and output voltage to set the on-time one-shot timer. The on-time is inversely proportional to the input voltage and proportional to the output voltage. It can be calculated using the following equation:

$$t_{ON} = \frac{V_{OUT}}{V_{IN} \times f_s}$$

VOUT is the output voltage

VIN is the input voltage

fs is the switching frequency

After an ON-time period, the AP65353 goes into the OFF-time period. The OFF-time period length depends on VFB in most cases. It will end when the FB voltage decreases below 0.76V, at which point the ON-time period is triggered. If the OFF-time period is less than the minimum OFF time, the minimum OFF time will be applied, which is about 260ns typical.

**Power Save Mode**

The AP65353 is designed with Power Save Mode (PSM) at light load conditions for high efficiency. The AP65353 automatically reduces the switching frequency and changes the Ton time to Tmin-on time during a light load condition to get high efficiency and low output ripple. As the output current decreases from heavy load condition, the inductor current decreases as well, eventually comes close to zero current, which is the boundary between CCM and DCM. The low side MOSFET is turned off when the inductor current reaches zero level. The load is provided only by output capacitor, when FB voltage is lower than 0.76V, the next ON cycle begins. The on-time is the minimum on time that benefits for decreasing VOUT ripple at light load condition. When the output current increases from light to heavy load the switching frequency increases to keep output voltage. The transition point to light load operation can be calculated using the following equation:

$$I_{LOAD} = \frac{V_{IN} - V_{OUT}}{2L} \times T_{ON}$$

TON is on-time

**Enable**

Above the ‘EN high-level input voltage’, the internal regulator is turned on and the quiescent current can be measured above this threshold. The enable (EN) input allows the user to control turning on or off the regulator. To enable the AP65353, EN must be pulled above the ‘EN high-level input voltage.’ To disable the AP65353, EN must be pulled below ‘EN low-level input voltage.’

In Figure 3, EN is a high voltage input that can be safely connected to VIN (up to 18V) directly or through a 100kΩ pull-up to VIN for automatic start-up.

**Application Information** (continued)

**Soft-Start**

The soft-start time of the AP65353 is programmable by selecting different  $C_{SS}$  values. When the EN pin becomes high, the  $C_{SS}$  is charged by a current source, generating a ramp signal fed into the non-inverting input of the error comparator. Reference voltage  $V_{REF}$ , or the internal soft-start voltage SS, (whichever is smaller), dominates the behavior of the non-inverting inputs of the error amplifier. Accordingly, the output voltage will follow the SS signal and ramp up smoothly to its target level. The capacitor value required for a given soft-start ramp time can be expressed as:

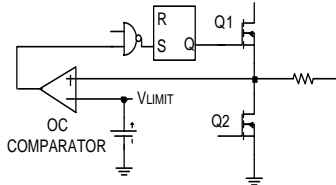
$$t_{SS} = 63 \times 10^3 \times C_{SS}$$

Where  $C_{SS}$  is the required capacitor between SS pin and PGND,  $t_{SS}$  is the desired soft-start time.

**Overcurrent Protection (OCP)**

Figure 4 shows the overcurrent protection (OCP) scheme of AP65353. In each switching cycle, the inductor current is sensed by monitoring the low-side MOSFET during the OFF period. When the voltage between PGND pin and SW pin is lower than the overcurrent trip level,  $V_{LIMIT}$ , the OCP will be triggered and the controller keeps the OFF state. A new switching cycle will begin when the measured voltage is higher than limit voltage. After  $6\mu s$ , the internal OCL (Overcurrent Logic) threshold is set to a lower level and SS pin is discharged such that output is 0V. Then the switching action is blanked out for one  $t_{SS}$  before soft start re-initiated and OCP threshold is restored to higher value.

Because the  $R_{DS(ON)}$  of MOSFET increases with temperature,  $V_{LIMIT}$  has 4ppm/°C temperature coefficient to compensate this temperature dependency of  $R_{DS(ON)}$ .



**Figure 4 Overcurrent Protection Scheme**

**Undervoltage Lockout**

The AP65353 provides an undervoltage lockout circuit to prevent it from undefined status during startup. The UVLO circuit shuts down the device when  $V_{IN}$  drops below 3.45V. The UVLO circuit has 320mV hysteresis, which means the device starts up again when  $V_{REG}$  rises to 3.75V (non-latch).

**PG Comparator**

PG is an open drain output controlled by a comparator connected to the feedback signal. If FB exceeds 90% of the internal reference voltage, PG will be high impedance. Otherwise, the PG output is connected to PGND.

**Thermal shutdown**

If the junction temperature of the device reaches the thermal shutdown limit of +150°C, the AP65353 shuts itself off, and both HMOS and LMOS will be turned off. The output is discharged with the internal transistor. When the junction cools to the required level (+130°C nominal), the device initiates soft-start as during a normal power-up cycle.

**Power Derating Characteristics**

To prevent the regulator from exceeding the maximum junction temperature, some thermal analysis is required. The temperature rise is given by:

$$T_{RISE} = PD \cdot (\theta_{JA})$$

Where PD is the power dissipated by the regulator and  $\theta_{JA}$  is the thermal resistance from the junction of the die to the ambient temperature. The junction temperature,  $T_J$ , is given by:

$$T_J = T_A + T_{RISE}$$

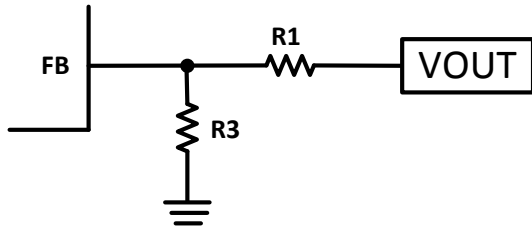
$T_A$  is the ambient temperature of the environment. The actual junction temperature should not exceed the absolute maximum junction temperature of +125°C when considering the thermal design.

**Setting the Output Voltage**

The output voltage can be adjusted from 0.76 using an external resistor divider. Table 1 shows a list of resistor selection for common output voltages. Resistor R1 is selected based on a design tradeoff between efficiency and output voltage accuracy. For high values of R1 there is less current consumption in the feedback network. However, the tradeoff is output voltage accuracy due to the bias current in the error amplifier. R1 can be determined by the following equation:

$$R_1 = R_3 \cdot \left( \frac{V_{OUT}}{0.765} - 1 \right)$$

**Application Information** (cont.)



**Figure 5 Feedback Divider Network**

| Output Voltage (V) | R1 (kΩ) | R3 (kΩ) |
|--------------------|---------|---------|
| 1                  | 6.81    | 22.1    |
| 1.05               | 8.25    | 22.1    |
| 1.2                | 12.7    | 22.1    |
| 1.5                | 21.5    | 22.1    |
| 1.8                | 30.1    | 22.1    |
| 2.5                | 49.9    | 22.1    |
| 3.3                | 73.2    | 22.1    |
| 5                  | 124     | 22.1    |

**Table 1 Resistor Selection for Common Output**

**Inductor**

Calculating the inductor value is a critical factor in designing a buck converter. For most designs, the following equation can be used to calculate the inductor value:

$$L = \frac{V_{OUT} \cdot (V_{IN} - V_{OUT})}{V_{IN} \cdot \Delta I_L \cdot f_S}$$

Where  $\Delta I_L$  is the inductor ripple current and  $f_S$  is the buck converter switching frequency.

Choose the inductor ripple current to be 30% of the maximum load current. The maximum inductor peak current is calculated from:

$$I_{L(MAX)} = I_{LOAD} + \frac{\Delta I_L}{2}$$

Peak current determines the required saturation current rating, which influences the size of the inductor. Saturating the inductor decreases the converter efficiency while increasing the temperatures of the inductor and the internal MOSFETs. Hence choosing an inductor with an appropriate saturation current rating is important.

A 1μH to 3.3μH inductor with a DC current rating of at least 25% higher than the maximum load current is recommended for most applications. For highest efficiency, the inductor’s DC resistance should be less than 100mΩ. Use a larger inductance for improved efficiency under light load conditions.

The phase boost can be achieved by adding an additional feed forward capacitor (C10) in parallel with R1.

| Output Voltage (V) | C10(pF) | L1 (μH) | C5+C9 (μF) |
|--------------------|---------|---------|------------|
| 1                  | —       | 1.0-1.5 | 22-68      |
| 1.05               | —       | 1.0-1.5 | 22-68      |
| 1.2                | —       | 1.0-1.5 | 22-68      |
| 1.5                | —       | 1.5     | 22-68      |
| 1.8                | 5-22    | 1.5     | 22-68      |
| 2.5                | 5-22    | 2.2     | 22-68      |
| 3.3                | 5-22    | 2.2     | 22-68      |
| 5                  | 5-22    | 3.3     | 22-68      |

**Table 2 Recommended Component Selection**

**Input Capacitor**

The input capacitor reduces the surge current drawn from the input supply and the switching noise from the device. The input capacitor has to sustain the ripple current produced during the on time on the upper MOSFET. It must have a low ESR to minimize the losses.

The RMS current rating of the input capacitor is a critical parameter that must be higher than the RMS input current. As a rule of thumb, select an input capacitor which has RMS rating greater than half of the maximum load current.

Due to large di/dt through the input capacitors, electrolytic or ceramics should be used. If a tantalum must be used it must be surge protected, otherwise, capacitor failure could occur. For most applications greater than 10μF, ceramic capacitor is sufficient.

**Application Information** (cont.)

**Output Capacitor**

The output capacitor keeps the output voltage ripple small, ensures feedback loop stability and reduces the overshoot of the output voltage. The output capacitor is a basic component for the fast response of the power supply. In fact, during load transient, for the first few microseconds, it supplies the current to the load. The converter recognizes the load transient and sets the duty cycle to maximum, but the current slope is limited by the inductor value.

Maximum capacitance required can be calculated from the following equation:

ESR of the output capacitor dominates the output voltage ripple. The amount of ripple can be calculated from the equation below:

$$V_{OUT\_RIPPLE} = \Delta I_{INDUCTOR} * ESR$$

An output capacitor with ample capacitance and low ESR is the best option. For most applications, a 22µF to 68µF ceramic capacitor will be sufficient.

$$C_O = \frac{L(I_{OUT} + \frac{\Delta I_{INDUCTOR}}{2})^2}{(\Delta V + V_{OUT})^2 - V_{OUT}^2}$$

Where ΔV is the maximum output voltage overshoot.

**Bootstrap Capacitor**

To ensure the proper operation, a ceramic capacitor must be connected between the VBST and SW pin. A 0.1µF ceramic capacitor is sufficient.

**VREG5 Capacitor**

To ensure the proper operation, a ceramic capacitor must be connected between the VREG5 and PGND pin. A 1µF ceramic capacitor is sufficient.

**PC Board Layout**

1. The AP65353 works at 3A load current, heat dissipation is a major concern in layout of the PCB. A 2oz Copper in both top and bottom layer is recommended.
2. Provide sufficient vias in the thermal exposed pad for heat dissipate to the bottom layer.
3. Provide sufficient vias in the Output capacitor PGND side to dissipate heat to the bottom layer.
4. Make the bottom layer under the device as PGND layer for heat dissipation. The PGND layer should be as large as possible to provide better thermal effect.
5. Make the Vin capacitors as close to the device as possible.
6. Make the VREG5 capacitor as close to the device as possible.
7. The thermal pad of the device should be soldered directly to the PCB exposed copper plane to work as a heatsink. The thermal vias in the exposed copper plane increase the heat transfer to the bottom layer.

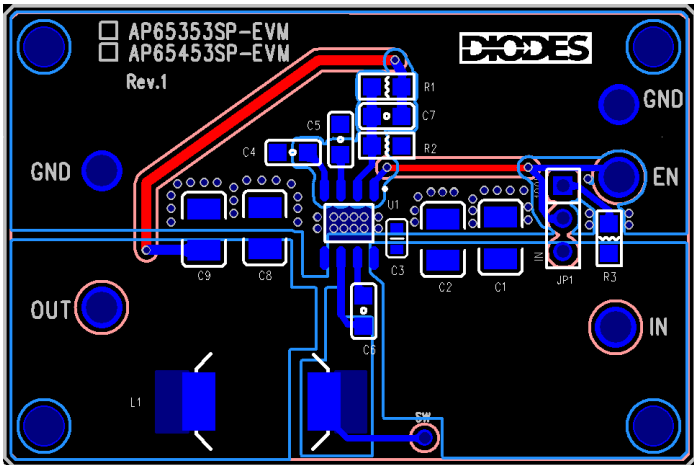
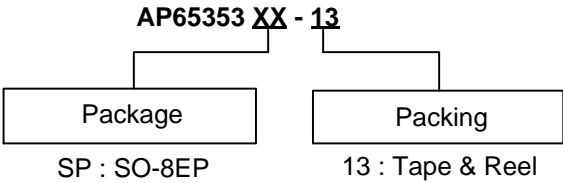


Figure 6 PC Board Layout

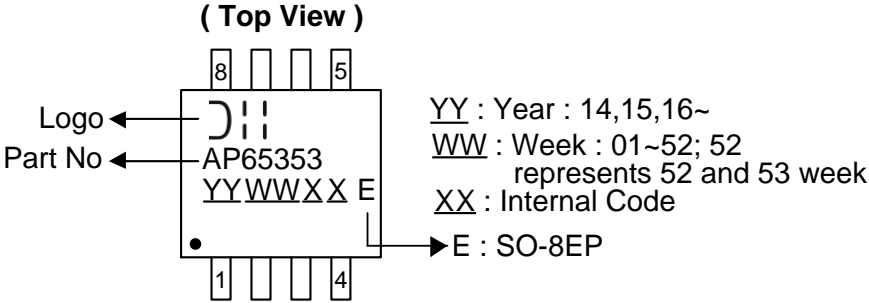
**Ordering Information**



| Part Number  | Package Code | Package | Identification Code | Tape and Reel |                    |
|--------------|--------------|---------|---------------------|---------------|--------------------|
|              |              |         |                     | Quantity      | Part Number Suffix |
| AP65353SP-13 | SP           | SO-8EP  | —                   | 2,500         | -13                |

**Marking Information**

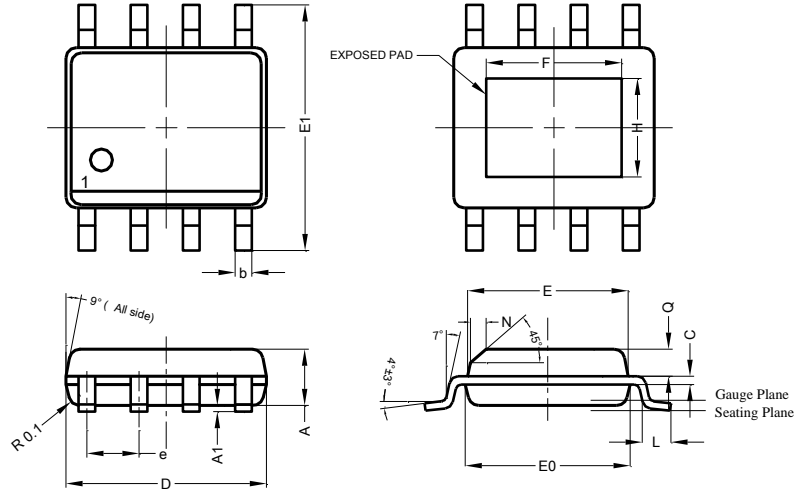
SO-8EP



**Package Outline Dimensions** (All dimensions in mm.)

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

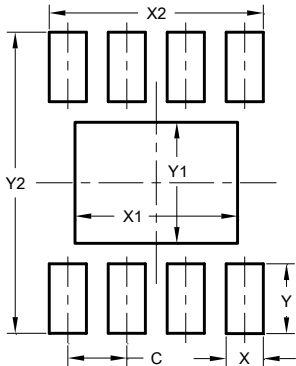
**SO-8EP**



| SO-8EP                      |      |      |      |
|-----------------------------|------|------|------|
| Dim                         | Min  | Max  | Typ  |
| A                           | 1.40 | 1.50 | 1.45 |
| A1                          | 0.00 | 0.13 | -    |
| b                           | 0.30 | 0.50 | 0.40 |
| C                           | 0.15 | 0.25 | 0.20 |
| D                           | 4.85 | 4.95 | 4.90 |
| E                           | 3.80 | 3.90 | 3.85 |
| E0                          | 3.85 | 3.95 | 3.90 |
| E1                          | 5.90 | 6.10 | 6.00 |
| e                           | -    | -    | 1.27 |
| F                           | 2.75 | 3.35 | 3.05 |
| H                           | 2.11 | 2.71 | 2.41 |
| L                           | 0.62 | 0.82 | 0.72 |
| N                           | -    | -    | 0.35 |
| Q                           | 0.60 | 0.70 | 0.65 |
| <b>All Dimensions in mm</b> |      |      |      |

**Suggested Pad Layout**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.



| Dimensions | Value (in mm) |
|------------|---------------|
| C          | 1.270         |
| X          | 0.802         |
| X1         | 3.502         |
| X2         | 4.612         |
| Y          | 1.505         |
| Y1         | 2.613         |
| Y2         | 6.500         |

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